

**AMENDMENTS TO THE SPECIFICATION**

Pages 19 and 20, the paragraph bridging these pages from page 19, line 26 to page 20, line 3, replace the bridging paragraph with:

That is, because the pad pitch of the semiconductor chip 2 is less than or equal to 1/2 of the minimum value of the tip pitch between the adjacent inner leads 1b, effectiveness of the QFP 6 mounting the semiconductor chip 2 having a narrow pad pitch can be enhanced.